1. Scope

These drawings for approval shall be applied to the Metal Film MELF resistors (MFM series) of lead-free manufactured.

2. Part Number

Part number of the Metal Film MELF Resistors is indentified by the series, size, power rating, tolerance, temperature coefficient, packing, special code and resistance value. The resistors are coated with layers of blue color lacquer.

Ex:

MFM	B	25S	F	C 2	R		100K
1.00	·				-	A	70 2

Series
Code
MFM

5	Size
C	ode
В=	0204
C=	0207
D=	0309

	Power
	Rating
2	25S = 0.25WS
	-50 = 0.5W
	50S = 0.5WS
	-50 = 0.5W

F	Re	sis	sta	nce)
•	To	le	rai	nce	
Γ	F	=	±1	1%	
l	G	=	±	2%	
L	J	=	±5	5%	

	T.C.R.
I	(ppm/°C)
Ī	$C1 = \pm 100$
l	$C2 = \pm 50$
l	$C3 = \pm 25$

Γ	Packaging
	Code
1	R=Tape/Reel
5	B=Bulk

Sp	ecia
C	ode
Ва	ase
(on
S	oec.

Resistance
Value
E 24 & E 196
100R = 100
10K = 10,000
1M = 1,000,000

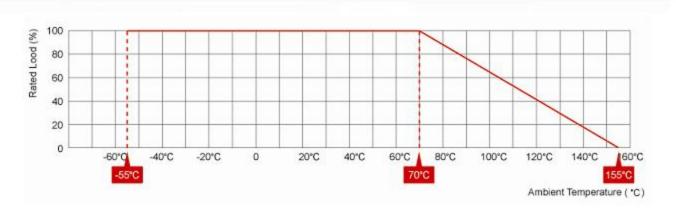
3. Specification

Series	Size	Power	T.C.R	Resis	tance Tol. & I	Range	Max.Working	Max.Overload
	Code	Rating	(x10 ⁻⁶ /K)	F(±1%)	G(±2%)	J(±5%)	Voltage	Voltage
		0.25W	±100	5M11-10M	8 4 0	0.1R-0.99R	200V	400V
MFMB25S	0204		±50	1R-5M1	1R-5M1	-		
			±25	100R-560K	-9	1-		
		0.25W 0207 0.5W	±100	5M11-10M	-	0.1R-0.99R	250V	500V
MFMC-25	0207 —		±50	1R-5M1	1R-5M1	-		
			±25	100R-560K	·=(-		
			±100	5M11-10M	127	0.1R-0.99R		
MFMC50S			±50	1R-5M1	1R-5M1	-		
			±25	4R7-560K	-	-		
	0309	0309 0.5W	±100	5M11-10M	i. ≡ £	0.1R-0.99R	350V	700V
MFMD-50			±50	1R-5M1	1R-5M1	1-		
			±25	100R-560K	-	16		

Note: Below or over this resistance on request.

Termination surface material is tin plating.

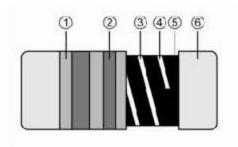
5. Derating Curve



For resistors operated in ambient temperatures above 70°C, power rating must be derated in accordance with the above curve.

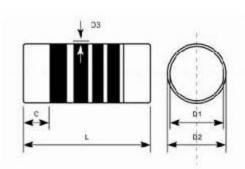


6. Construction



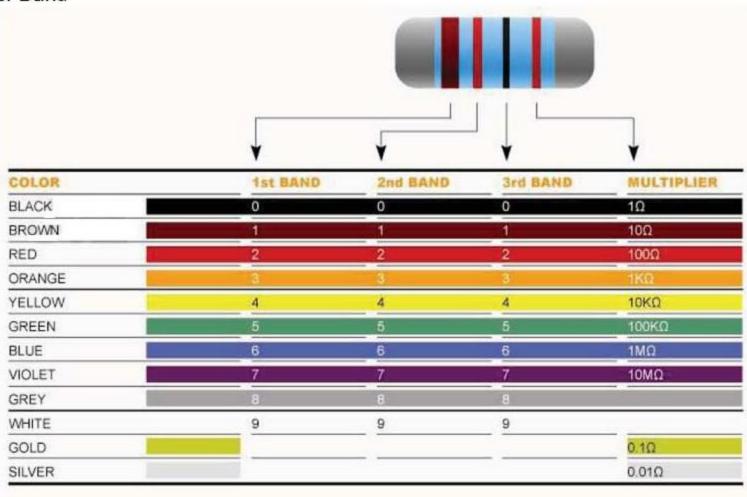
	Item	Material		
1	Insulation Coating	Epoxy Insulation (Color: Blue)		
2	Marking	Epoxy Resin		
3	Cutting Line	TEST CONTRACTOR OF THE PROPERTY OF THE PROPERT		
4	Ceramic Core	Aluminum Material		
(5)	Resistive Film	Metal Film		
6	Terminal	Terminal Material : Fe/Cu/Sn		

7. Dimension



o: .		Dime	ension (mm)		
Size code	L	D1	D2 Max	D3 Max	C Min
B (0204)	3.5±0.2	1.40±0.1	1.55	0.1	0.5
C (0207)	5.9±0.2	2.20±0.1	2.4	0.15	1.0
D (0309)	8.5±0.2	3.20±0.2	3.4	0.3	1.5

8. Color Band



Note:

The tolerance 1% with 4 bands for E96 & E24 series, the tolerance 5% with 3 bands for E24 series.



Metal Film MELF Resistors (lead-free)

9. Environmental characteristics

No.	Test Item	Performance Requirements	Test Methods (JIS-C-5201-1)		
1 T.C.R		Within specified T.C.R	+25°C/-55°C and +25°C/+125°C		
2	Solderability	More than 95% of the total area of the electrode part shall be covered with new solder	Temperature of solder: 235±5°C Dipping time: 3±0.5 sec		
3	Resistance to solvent	Epoxy Insulation coating can not be peeled	There are 3 circles, each circle takes 1 min.		
4.	Resistance to soldering heat	Based on the Iron cap loose standard , the change of the resistance value shall be within $\pm (0.5\% + 0.05\Omega)$	Temperature: 260±5°C Dipping time:10±1 sec		
5.	Short time overload	The change of the resistance valueshall be within ±(0.5%+0.05Ω)	V=√R×P×2.5 , 5 sec. V= Rated Voltage R=Resistance Value P=Power Rating Size code 0102 0204 0207 0309 Power Rating 1/8W 1/4W 1/2W 1/2W Votage Max 300V 400V 500V 700V		
6	Overload	Within specified tolerance	V=√R×P×3 , 2.5 sec. V= Rated Voltage R=Resistance Value P=Power Rating Size code 0102 0204 0207 0309 Power Rating 1/8W 1/4W 1/2W 1/2W Votage Max 300V 400V 500V 700V		
7.	Humidity resistance	The change of the resistance value shall be within ±(1%+0.05Ω)	40°C±2°C, 90%~95% RH, 1.5hr ON / 0.5hr OFF cycle, total test 1000hr.		
8.	Load Life test	The change of the resistance value shall be within ±(3%+0.05Ω)	Constant temperature chamber of 70°C±2°C,DC 1.5hr ON / 0.5hr OFF cycle, applied continuously for 1,000±48hr.		



Metal Film MELF Resistors (lead-free)

10. Standard Packing Quantity

Circ code	Ta	ape/Reel Q'ty (p	cs)	Bulk Q'ty (pcs)	Weight (g)	
Size code	Reel	Case	Carton	Bag	Reel/pc	Net/Kpcs
B (0204)	3,000	15,000	180,000	5,000	390.5	18
C (0207)	2,000	8,000	96,000	5,000	383.5	155
D (0309)	2,500	2,500	15,000	5,000	2,505	160

11. Embossed Taping & Tape/Reel dimension

▼Embossed taping dimension

Туре	W	Р	E	F	D	D ₁	Po	P ₂	A ₀	B ₀	K ₀	t
0204	8±0.1	4±0.1	1.75±0.1	3.5±0.05	1.5±0.1	1.0±0.1	4±0.1	2±0.1	1.6±0.1	3.70±0.1	1.65±0.1	0.22±0.05
0207	12±0.1	4±0.1	1.75±0.1	5.5±0.05	1.5±0.1	1.5±0.1	4±0.1	2±0.1	2.4±0.1	6.05±0.1	2.50±0.1	0.30±0.05
0309	16±0.1	8±0.1	1.75±0.1	7.5±0.10	1.5±0.1	1.5±0.1	4±0.1	2±0.1	3.5±0.1	8.85±0.1	3.50±0.1	0.35±0.05

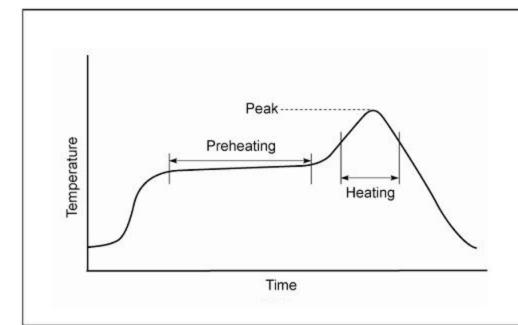
▼Tape/Reel dimension

Туре	ØΑ	ØB	ØC	W	Т
0204	178±1	60.0±0.5	13.0±0.2	9.0±0.5	12.0±0.15
0207	178±1	60.0±0.5	13.0±0.5	13.2±0.5	16.0±0.20
0309	330±1	100±1.0	13.0±0.5	17.0±0.5	21.5±0.20

- 12. Caution
- 12-1 Storage and usage method
- 12-2 Humidity gives damage to cap solderability, therefore, please keep environment.

Temperature: +5°C~+40°C Humidity: 55%~75%RH Storage limited: 12 months

- 12-3 Please follow the instruction to keep the material when it is unpacked.
- 12-4 When ambient temperature exceeds a rated ambient temperature, the resistance shall be applied on the derating curve by derating the load power.
- 12-5 Please avoid join many resistors in series or parallel when apply high voltage or high electric current.
- 12-6 Molding products by using regin might bring out resistance value change. Please keep away from Molding.
- 12-7 This products meet the RoHS Compliant.
- 13. Soldering: We recommend the following condition to keep products performance.
- 13-1 Conditions for reflow



<Reflow soldering (lead-free)>

Status	Temperature	Time		
Preheating	180°C _{Mex}	120 sec. _{Max}		
Heating	220°C _{Max}	60 sec. _{Max}		
Peak	260°C _{Max}	3 sec. _{Max}		

13-2 Flow soldering (lead-free)

Temperature : 260°C Max

Time: 10 sec. Max